

Electronic Patent Application Fee Transmittal

Application Number:	10537509			
Filing Date:	30-Nov-2005			
Title of Invention:	Method for cutting semiconductor substrate			
First Named Inventor/Applicant Name:	Fumitsugu Fukuyo			
Filer:	John G. Smith/Traci Thompson			
Attorney Docket Number:	46884-5388 (211285)			

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Extension - 3 months with \$0 paid	1253	1	1110	1110
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				1920